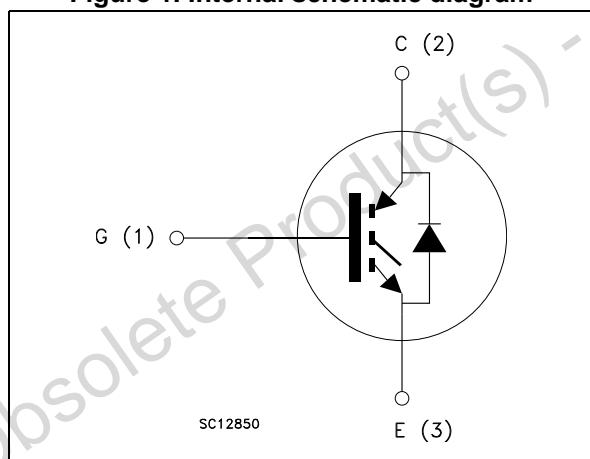


**Figure 1. Internal schematic diagram**



## Features

- Designed for soft commutation only
- Maximum junction temperature:  $T_J = 175^\circ\text{C}$
- Minimized tail current
- Low saturation voltage:  $V_{CE(\text{sat})} = 2.0\text{ V}$  (typ.) @  $I_C = 25\text{ A}$
- Tight parameters distribution
- Safe paralleling
- Low  $V_F$  soft recovery co-packaged diode
- Low thermal resistance
- Lead free package

## Applications

- Induction heating
- Microwave oven
- Resonant converters

## Description

These IGBTs are developed using an advanced proprietary trench gate field-stop structure and performance is optimized in both conduction and switching losses. A freewheeling diode with a low drop forward voltage is co-packaged. The result is a product specifically designed to maximize efficiency for any resonant and soft-switching application.

**Table 1. Device summary**

Order code	Marking	Package	Packaging
STGW28IH120DF	GW28IH120DF	TO-247	Tube
STGWT28IH120DF	GWT28IH120DF	TO-3P	Tube

# 1 Electrical ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
$V_{CES}$	Collector-emitter voltage ( $V_{GE} = 0$ )	1200	V
$I_C$	Continuous collector current at $T_C = 25^\circ\text{C}$	50	A
$I_C$	Continuous collector current at $T_C = 100^\circ\text{C}$	25	A
$I_{CP}^{(1)}$	Pulsed collector current	100	A
$V_{GE}$	Gate-emitter voltage	$\pm 20$	V
$I_F$	Continuous forward current at $T_C = 25^\circ\text{C}$	50	A
$I_F$	Continuous forward current at $T_C = 100^\circ\text{C}$	25	A
$I_{FP}^{(1)}$	Pulsed forward current	100	A
$P_{TOT}$	Total dissipation at $T_C = 25^\circ\text{C}$	375	W
$T_{STG}$	Storage temperature range	- 55 to 150	$^\circ\text{C}$
$T_J$	Operating junction temperature	- 40 to 175	$^\circ\text{C}$

1. Pulse width limited by maximum junction temperature and turn-off within RBSOA

Table 3. Thermal data

Symbol	Parameter	Value	Unit
$R_{thJC}$	Thermal resistance junction-case IGBT	0.4	$^\circ\text{C}/\text{W}$
$R_{thJC}$	Thermal resistance junction-case diode	1.47	$^\circ\text{C}/\text{W}$
$R_{thJA}$	Thermal resistance junction-ambient	50	$^\circ\text{C}/\text{W}$

## 2 Electrical characteristics

$T_J = 25^\circ\text{C}$  unless otherwise specified.

Table 4. Static characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(\text{BR})\text{CES}}$	Collector-emitter breakdown voltage ( $V_{\text{GE}} = 0$ )	$I_C = 2 \text{ mA}$	1200			V
$V_{\text{CE}(\text{sat})}$	Collector-emitter saturation voltage	$V_{\text{GE}} = 15 \text{ V}, I_C = 25 \text{ A}$		2		V
		$V_{\text{GE}} = 15 \text{ V}, I_C = 25 \text{ A}$ $T_J = 125^\circ\text{C}$		2.25		
		$V_{\text{GE}} = 15 \text{ V}, I_C = 25 \text{ A}$ $T_J = 175^\circ\text{C}$		2.35		
		$V_{\text{GE}} = 15 \text{ V}, I_C = 50 \text{ A}$		2.55		
$V_F$	Forward on-voltage	$I_F = 25 \text{ A}$		1.3		V
		$I_F = 25 \text{ A}$ $T_J = 125^\circ\text{C}$		TBD		V
		$I_F = 25 \text{ A}$ $T_J = 175^\circ\text{C}$		TBD		V
$V_{\text{GE}(\text{th})}$	Gate threshold voltage	$V_{\text{CE}} = V_{\text{GE}}, I_C = 1 \text{ mA}$		6.0		V
$I_{\text{CES}}$	Collector cut-off current ( $V_{\text{GE}} = 0$ )	$V_{\text{CE}} = 1200 \text{ V}$			250	$\mu\text{A}$
$I_{\text{GES}}$	Gate-emitter leakage current ( $V_{\text{CE}} = 0$ )	$V_{\text{GE}} = \pm 20 \text{ V}$			250	nA

Table 5. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{\text{ies}}$	Input capacitance	$V_{\text{CE}} = 25 \text{ V}, f = 1 \text{ MHz},$ $V_{\text{GE}} = 0$	-	3500	-	pF
$C_{\text{oes}}$	Output capacitance		-	120	-	pF
$C_{\text{res}}$	Reverse transfer capacitance		-	22	-	pF
$Q_g$	Total gate charge	$V_{\text{CC}} = 600 \text{ V}, I_C = 25 \text{ A},$ $V_{\text{GE}} = 15 \text{ V}$ , see <a href="#">Figure 4</a>	-	88	-	nC
$Q_{\text{ge}}$	Gate-emitter charge		-	20	-	nC
$Q_{\text{gc}}$	Gate-collector charge		-	24	-	nC

Table 6. IGBT switching characteristics (inductive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(\text{off})}$	Turn-off delay time	$V_{CE} = 600 \text{ V}$ , $I_C = 25 \text{ A}$ , $R_G = 22 \Omega$ , $V_{GE} = 15 \text{ V}$ , see <a href="#">Figure 2</a>		TBD		ns
$t_f$	Current fall time		-	TBD	-	ns
$E_{\text{off}}^{(1)}$	Turn-off switching losses		-	0.93	-	mJ
$t_{d(\text{off})}$	Turn-off delay time	$V_{CE} = 600 \text{ V}$ , $I_C = 25 \text{ A}$ , $R_G = 22 \Omega$ , $V_{GE} = 15 \text{ V}$ , $T_J = 175 \text{ }^\circ\text{C}$ , see <a href="#">Figure 2</a>		TBD		ns
$t_f$	Current fall time		-	TBD	-	ns
$E_{\text{off}}^{(1)}$	Turn-off switching losses		-	1.85	-	mJ

1. Turn-off losses include also the tail of the collector current.

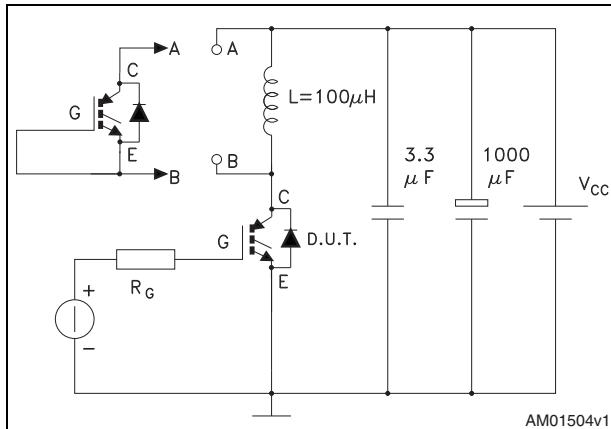
Table 7. IGBT switching characteristics (capacitive load)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$E_{\text{off}}^{(1)}$	Turn-off switching losses	$V_{CC} = 900 \text{ V}$ , $R_G = 10 \Omega$ , $I_C = 50 \text{ A}$ , $L = 500 \mu\text{H}$ , $C_{\text{ssub}} = 300 \text{ nF}$ , see <a href="#">Figure 3</a>	-	235	-	$\mu\text{J}$
		$V_{CC} = 900 \text{ V}$ , $R_G = 10 \Omega$ , $I_C = 50 \text{ A}$ , $L = 500 \mu\text{H}$ , $C_{\text{ssub}} = 300 \text{ nF}$ , $T_J = 175 \text{ }^\circ\text{C}$ , see <a href="#">Figure 3</a>	-	410	-	

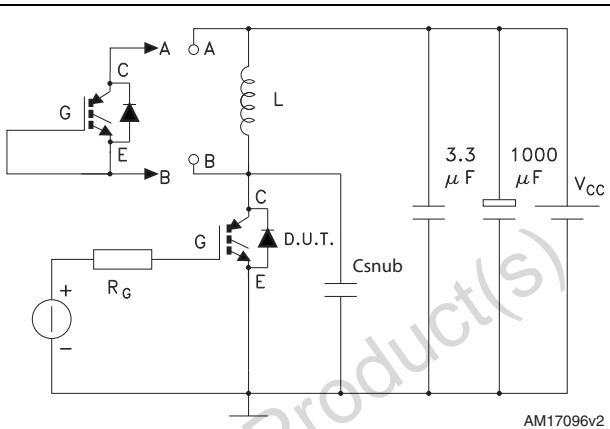
1. Turn-off losses include also the tail of the collector current.

### 3 Test circuits

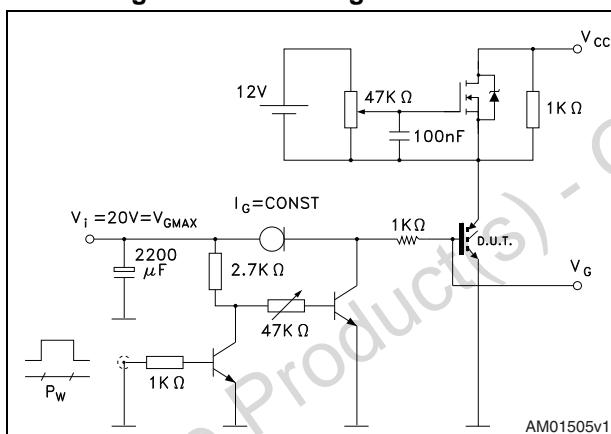
**Figure 2. Test circuit for inductive load switching**



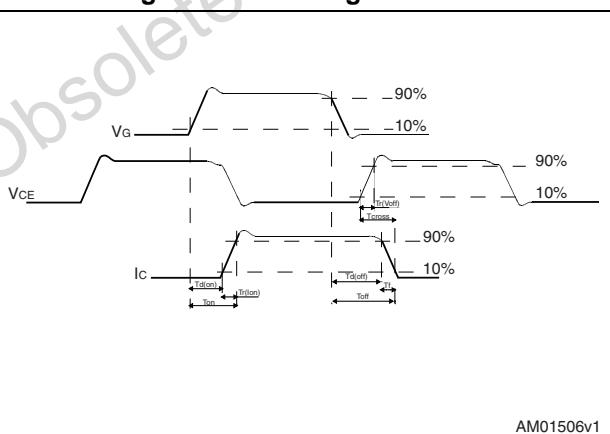
**Figure 3. Test circuit for capacitive load switching**



**Figure 4. Gate charge test circuit**



**Figure 5. Switching waveform**



## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com).  
ECOPACK is an ST trademark.

**Table 8. TO-247 mechanical data**

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

Figure 6. TO-247 drawing

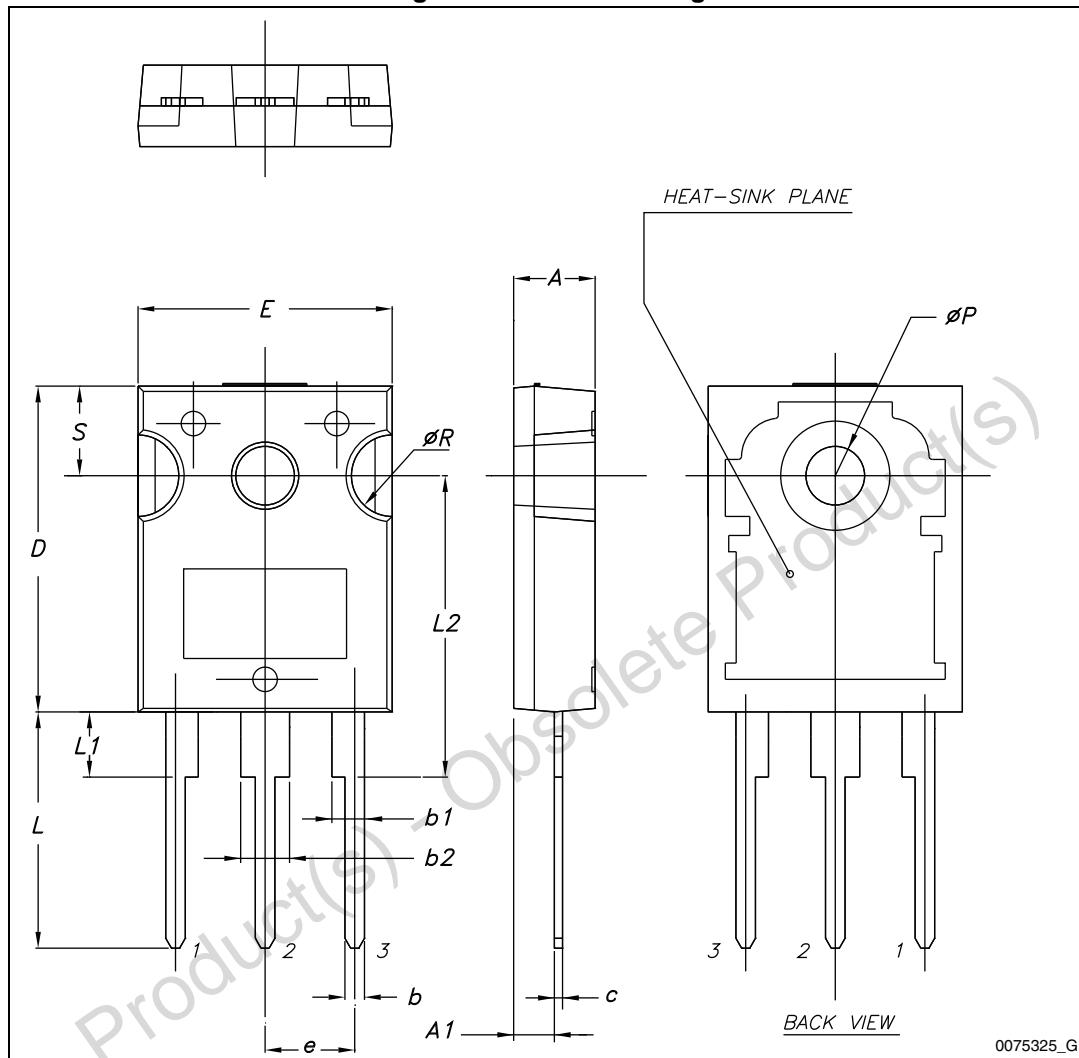
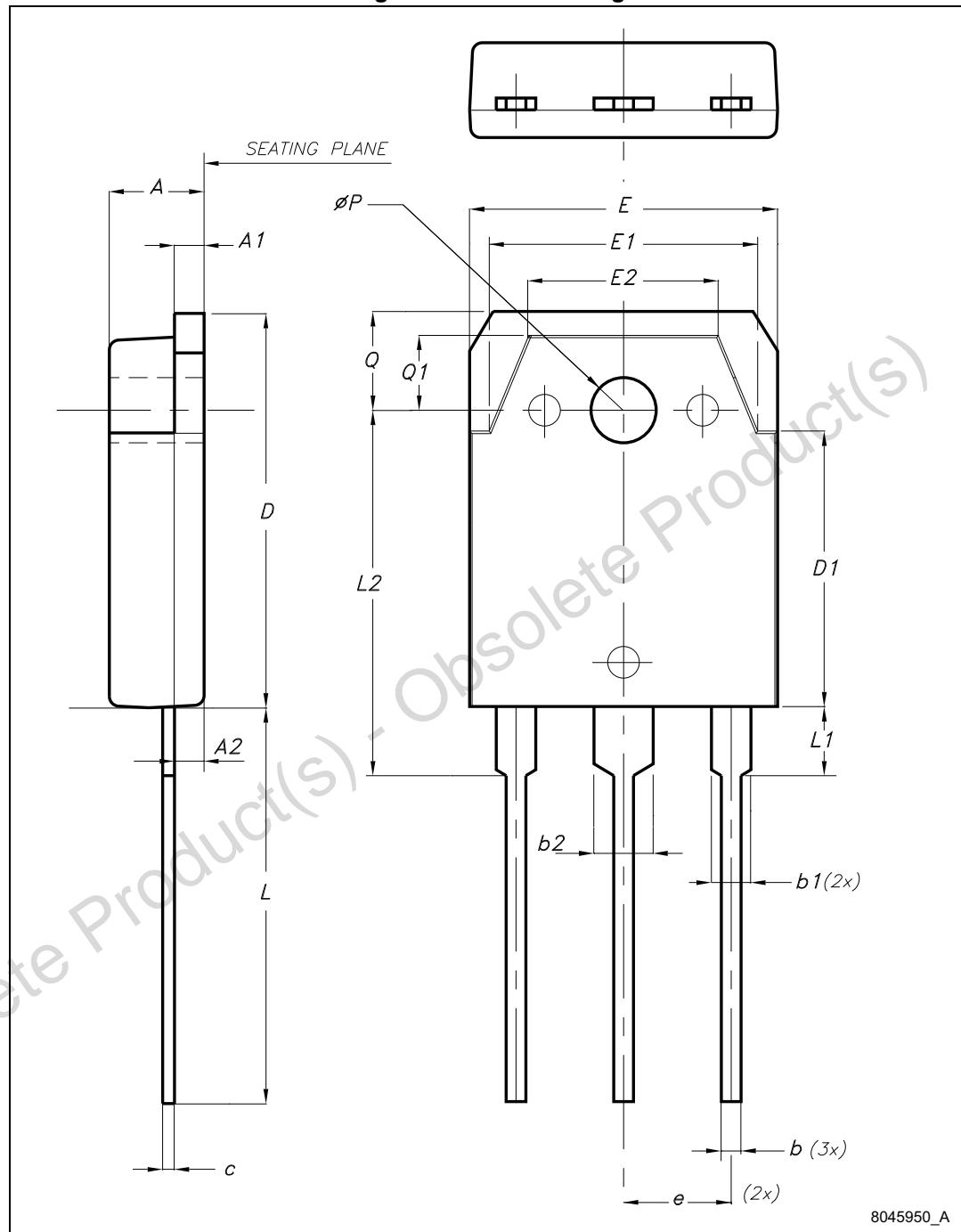


Table 9. TO-3P mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.60		5
A1	1.45	1.50	1.65
A2	1.20	1.40	1.60
b	0.80	1	1.20
b1	1.80		2.20
b2	2.80		3.20
c	0.55	0.60	0.75
D	19.70	19.90	20.10
D1		13.90	
E	15.40		15.80
E1		13.60	
E2		9.60	
e	5.15	5.45	5.75
L	19.50	20	20.50
L1		3.50	
L2	18.20	18.40	18.60
øP	3.10		3.30
Q		5	
Q1		3.80	

Figure 7. TO-3P drawing



## 5 Revision history

Table 10. Document revision history

Date	Revision	Changes
07-Feb-2012	1	Initial release.
28-Nov-2012	2	Added Section 2.1 Electrical characteristics (curves).
08-Feb-2013	3	Modified title in cover page. Removed Section 2.1. Added new order code STGW28IH120DF and mechanical data <a href="#">Table 8 on page 6</a> , <a href="#">Figure 6 on page 7</a> .
14-Mar-2013	4	Modified title, features and description in cover page.

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